MULTI-INNO TECHNOLOGY CO., LTD.

www.multi-inno.com

LCD MODULE SPECIFICATION

Model : MI0570ST-2

For Customer's Acceptance:

Customer	
Approved	
Comment	

Revision	1.1
Engineering	
Date	2012-12-26
Our Reference	

REVISION RECORD

REV NO.	REV DATE	CONTENTS	REMARKS
1.0	2012-11-26	First Release	
1.1	2012-12-26	Change CTP IC	

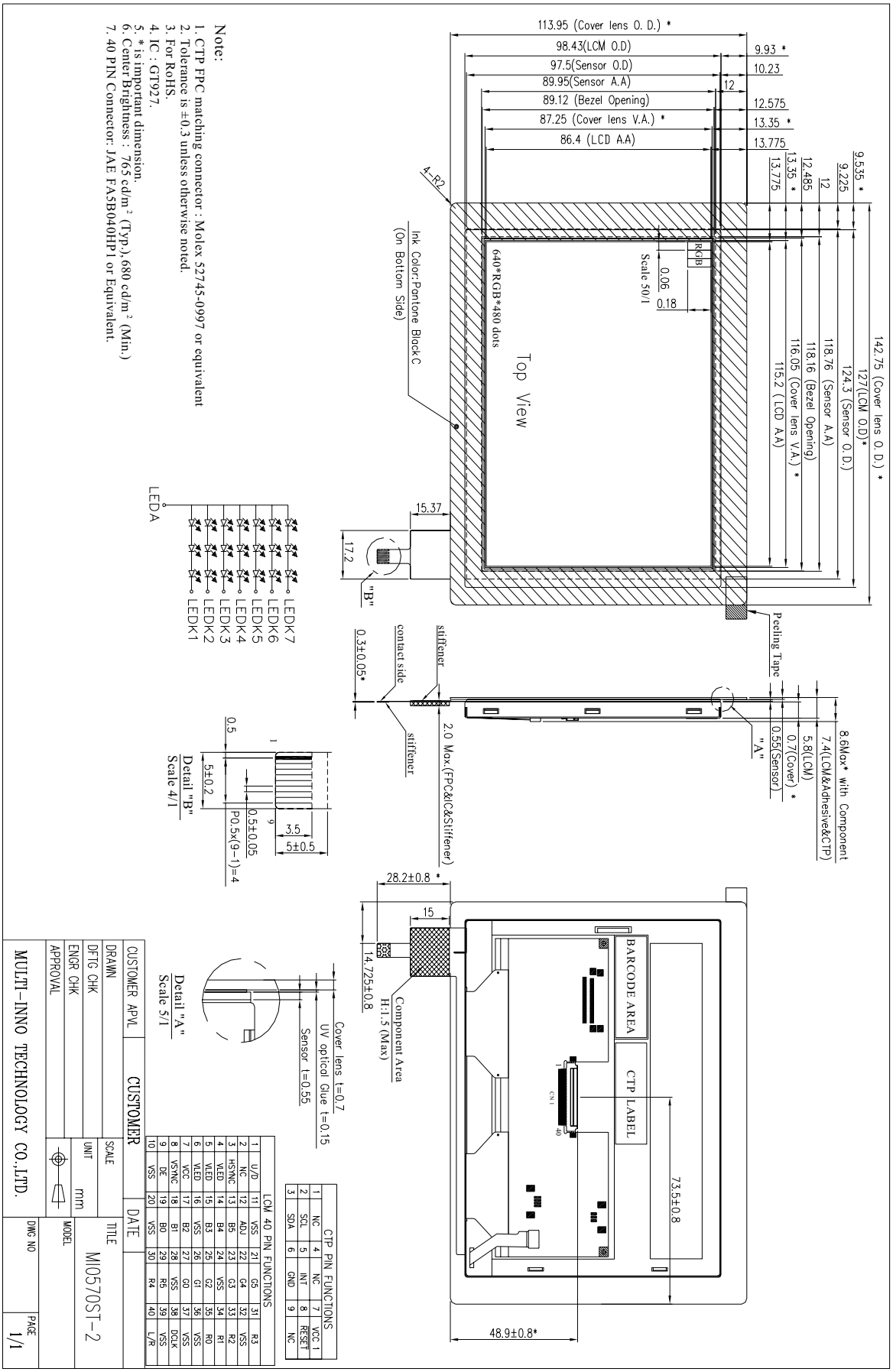
CONTENTS

■ GENERAL INFORMATION

Item	Contents	Unit
LCD type	TFT/Normally white	/
Size	5.7	Inch
Viewing direction	6:00	O' Clock
Gray scale inversion direction	12:00	O' Clock
LCM (W × H × D)	142.75×113.95×8.60	mm^3
Active area (W×H)	115.2×86.4	mm^2
Dot pitch (W×H)	0.06 × 0.18	mm^2
Number of dots	640 (RGB) × 480	/
Backlight type	21 LEDs	/
Interface type	18 bits RGB	/
Color depth	262K	/
Pixel configuration	R.G.B stripe	/
Surface treatment	Clear	/
Input voltage	3.3	V
With/Without TSP	With CTP	/
Weight	152.0	g

Note 1:Viewing direction for best image quality is different from TFT definition, there is a 180 degree shift.
Note 2: RoHS compliant;
Note 3: LCM weight tolerance: ± 5%.

■ EXTERNAL DIMENSIONS



■ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Power supply voltage	VCC	-0.3	5.0	V
Logic input voltage	VI	-0.3	VCC+0.3	V
Operating temperature	T_{OP}	-10	60	°C
Storage temperature	T_{ST}	-20	70	°C
Humidity	RH	-	90%(Max60°C)	RH

■ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Min	Typ	Max	Unit
Power supply voltage for LCD	VCC	3.0	3.3	3.6	V
Power supply current for LCD	ICC	-	111	140	mA
Power supply voltage for LED	V_{LED}	4.5	5.0	5.5	V
Power supply current for LED	I_{LED}	-	333	400	mA
Input voltage ' H ' level	V_{IH}	0.7VCC	-	VCC	V
Input voltage ' L ' level	V_{IL}	0	-	0.3VCC	V
Ripple voltage	V_{RF}	-	-	100	mV_{P-P}
ADJ frequency		19K	20K	21K	Hz
ADJ input voltage	V_{IH}	3.0	-	3.3	V
	V_{IL}	0	-	0.3	V
LED dice life time		-	50000	-	Hr

Note 1: The “LED dice life time” is defined as the brightness decrease to 50% original brightness that the ambient temperature is 22 and LED dice current=20mA

■ELECTRO-OPTICAL CHARACTERISTICS

Item		Symbol	Condition	Min	Typ	Max	Unit	Remark	Note
Response time		Tr+Tf	θ=0° ∅=0° Ta=25℃	---	50	---	ms	FIG 1.	4
Contrast ratio		Cr		200	300	---	---	FIG 2.	1
Luminance uniformity		δ WHITE		70	80	---	%	FIG 2.	3
Surface Luminance		Lv		680	765	---	cd/m^2	FIG 2.	2
Viewing angle range		θ	∅ = 90°	50	60	---	deg	FIG 3.	6
			∅ = 270°	30	40	---	deg	FIG 3.	
			∅ = 0°	60	70	---	deg	FIG 3.	
			∅ = 180°	60	70	---	deg	FIG 3.	
CIE (x, y) chromaticity	Red	x	θ=0° ∅=0° Ta=25℃	0.565	0.615	0.665		FIG 2.	5
		y		0.310	0.360	0.410			
	Green	x		0.295	0.345	0.395			
		y		0.490	0.540	0.590			
	Blue	x		0.098	0.148	0.198			
		y		0.056	0.106	0.156			
	White	x		0.259	0.309	0.359			
		y		0.270	0.320	0.370			
Image sticking	-	tis	2 hours	---	---	2	Sec	-	8

Note 1. Contrast Ratio(CR) is defined mathematically as For more information see FIG 2.

$$\text{Contrast Ratio} = \frac{\text{Average Surface Luminance with all white pixels (P1, P2, P3, P4, P5)}}{\text{Average Surface Luminance with all black pixels (P1, P2, P 3,P4, P5)}}$$

Note 2. Surface luminance is the LCD surface from the surface with all pixels displaying white. For more information see FIG 2.

Lv = Average Surface Luminance with all white pixels (P1, P2, P 3, P4, P5)

Note 3. The uniformity in surface luminance ， δ WHITE is determined by measuring luminance at each test position 1 through 5, and then dividing the maximum luminance of 5 points luminance by minimum luminance of 5 points luminance. For more information see FIG 2.

$$\delta\ \text{WHITE} = \frac{\text{Minimum Surface Luminance with all white pixels (P1, P2, P 3, P4, P5)}}{\text{Maximum Surface Luminance with all white pixels (P1, P2, P 3, P4, P5)}}$$

Note 4. Response time is the time required for the display to transition from White to black(Rise Time, Tr) and from black to white(Decay Time, Tf). For additional information see FIG 1. The test equipment is Autronic-Melchers's ConoScope. Series.

Note 5. CIE (x, y) chromaticity，The x, y value is determined by measuring luminance at each test position 1 through 5,and then make average value.

Note 6. Viewing angle is the angle at which the contrast ratio is greater than 2. For TFT module the conrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 3.

Note 7. For viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope. Series Instruments For contrast ratio, Surface Luminance, Luminance uniformity, CIE The test data is base on TOPCON's BM-5 photo detector.

Note 8: Definition of Image sticking (tis):
Continuously display the test pattern shown in the figure below for 2 hours. Then display a completely white screen. The previous image shall not persist more than 2 sec at 25 °C

Image sticking pattern

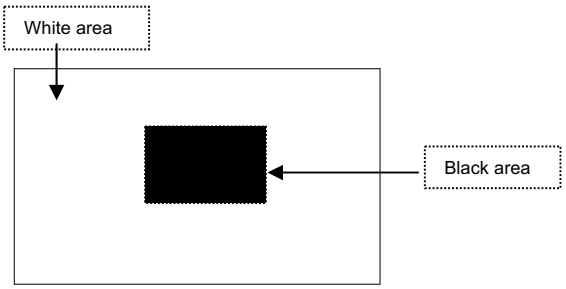


FIG. 1 The definition of Response Time

The response time is defined as the following figure and shall be measured by switching the input signal for "black" and "white".

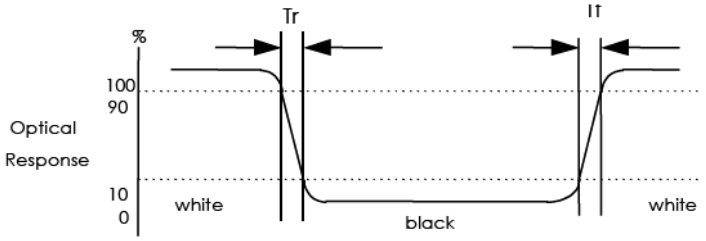
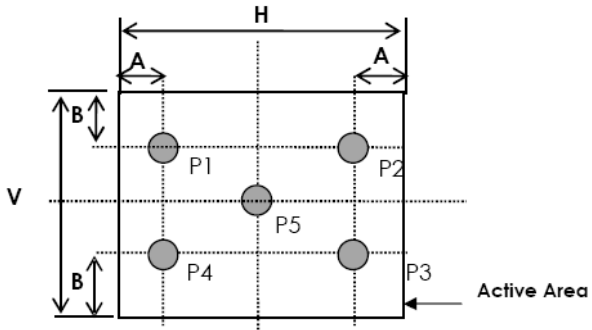
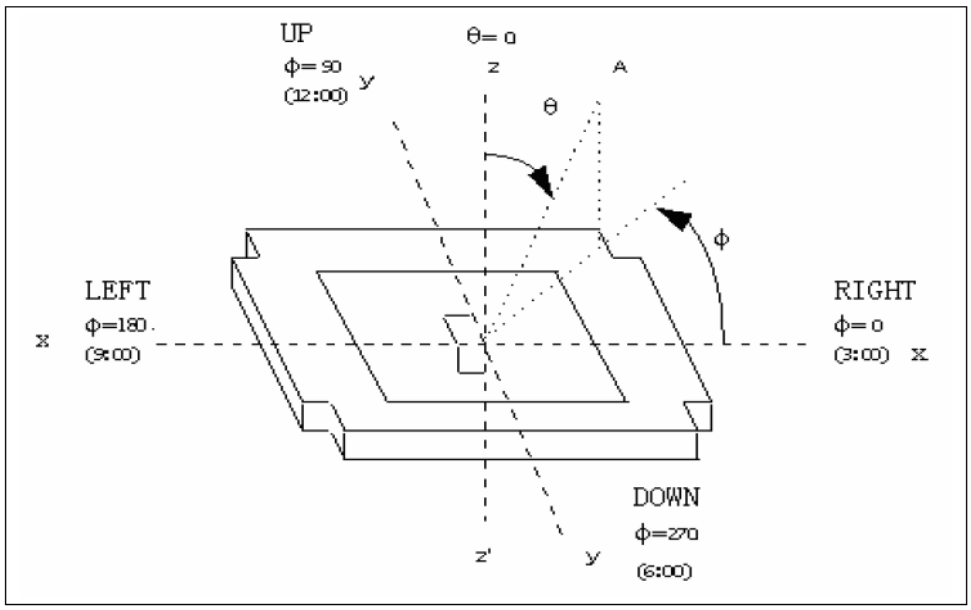


FIG. 2 Measuring method for Contrast ratio, surface luminance, Luminance uniformity , CIE (x, y) chromaticity



A : 5 mm
B : 5 mm
H,V : Active Area
Light spot size ∅=7mm, 500mm distance from the LCD surface to detector lens
measurement instrument is TOPCON's luminance meter BM-5

FIG. 3 The definition of viewing angle



■INTERFACE DESCRIPTION

Pin NO.	SYMBOL	DESCRIPTION
1	U/D	Up or Down Display Control
2	NC	No Connection
3	Hsync	Horizontal SYNC.
4	VLED	Power Supply for LED Driver circuit
5	VLED	Power Supply for LED Driver circuit
6	VLED	Power Supply for LED Driver circuit
7	Vcc	Power Supply for LCD
8	Vsync	Vertical SYNC.
9	DE	Data Enable
10	VSS	Power Ground
11	VSS	Power Ground
12	ADJ	Brightness control for LED B/L
13	B5	Blue Data 5 (MSB)
14	B4	Blue Data 4
15	B3	Blue Data 3
16	Vss	Power Ground
17	B2	Blue Data 2
18	B1	Blue Data 1
19	B0	Blue Data 0 (LSB)
20	Vss	Power Ground
21	G5	Green Data 5 (MSB)
22	G4	Green Data 4
23	G3	Green Data 3
24	Vss	Power Ground
25	G2	Green Data 2
26	G1	Green Data 1
27	G0	Green Data 0 (LSB)
28	Vss	Power Ground
29	R5	Red Data 5 (MSB)
30	R4	Red Data 4
31	R3	Red Data 3
32	Vss	Power Ground
33	R2	Red Data 2
34	R1	Red Data 1
35	R0	Red Data 0
36	VSS	Power Ground
37	VSS	Power Ground
38	DCLK	Clock Signals ; Latch Data at the Falling Edge
39	Vss	Power Ground
40	L/R	Left or Right Display Control

Remarks：

1) ADJ is brightness control Pin. The larger of the pulse duty is, the higher of the brightness.
2) ADJ signal is 0~3.3V.Operation frequency is 20KHz
3) VSS PIN must be grounding, can not be floating.
4) U/D and L/R control Function

L/R	U/D	Function
1	0	Normally display
0	0	Left and Right opposite
1	1	Up and Down opposite
0	1	Left and Right opposite，Up and Down opposite

5)If DE signal is fixed low, SYNC mode is used. Otherwise, DE mode is used.

8.1 Power Signal Sequence

Remarks:

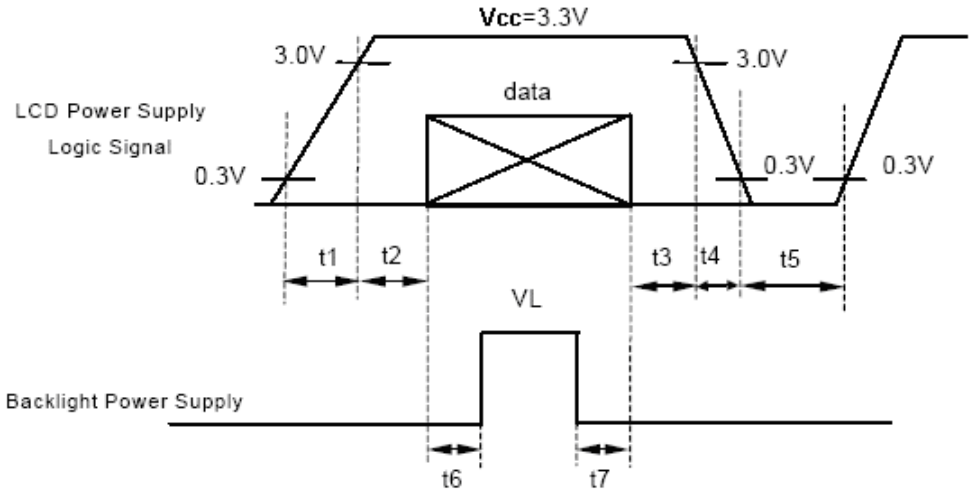
*1) Power Signal sequence:

t1 ≤10ms : 1 sec≤ t5

50ms≤ t2 : 200ms ≤t6

0<t3 ≤50ms: 200ms≤ t7

0<t4 ≤10ms

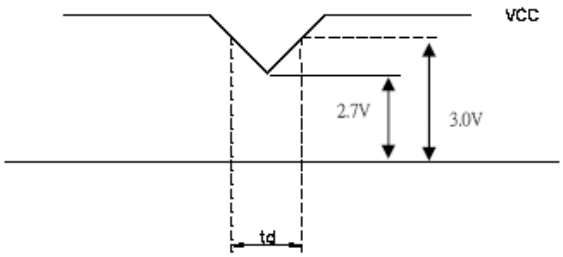


Data: RGB DATA, DCLK, DE

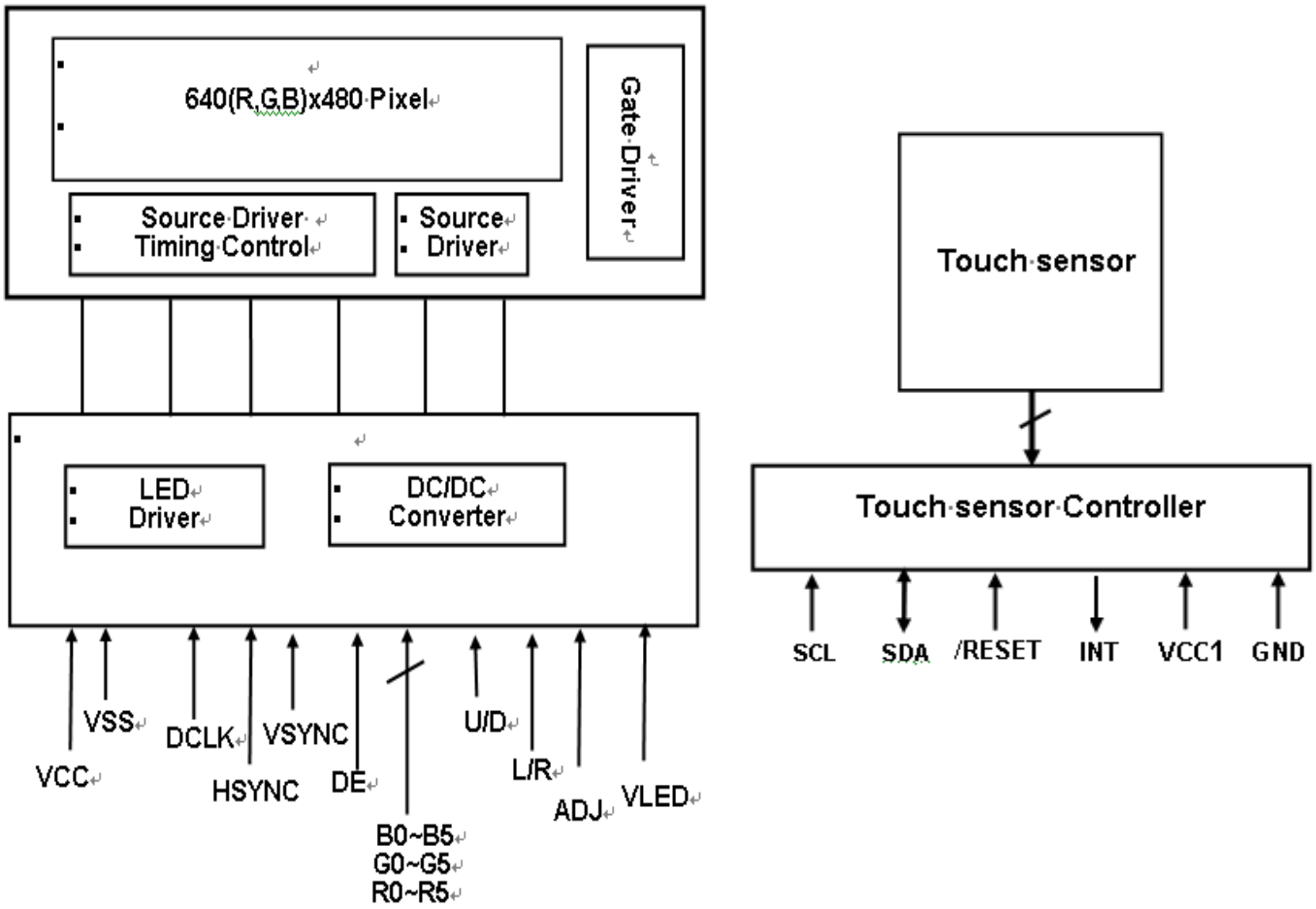
*2) VCC-dip condition:

(1) 2.7 V ≤VCC <3.0V,td ≤ 10 ms

(2) VCC＞3.0V,VCC-dip condition should be the same with VCC-turn-on condition。



■BLOCK DIAGRAM



■ APPLICATION NOTES

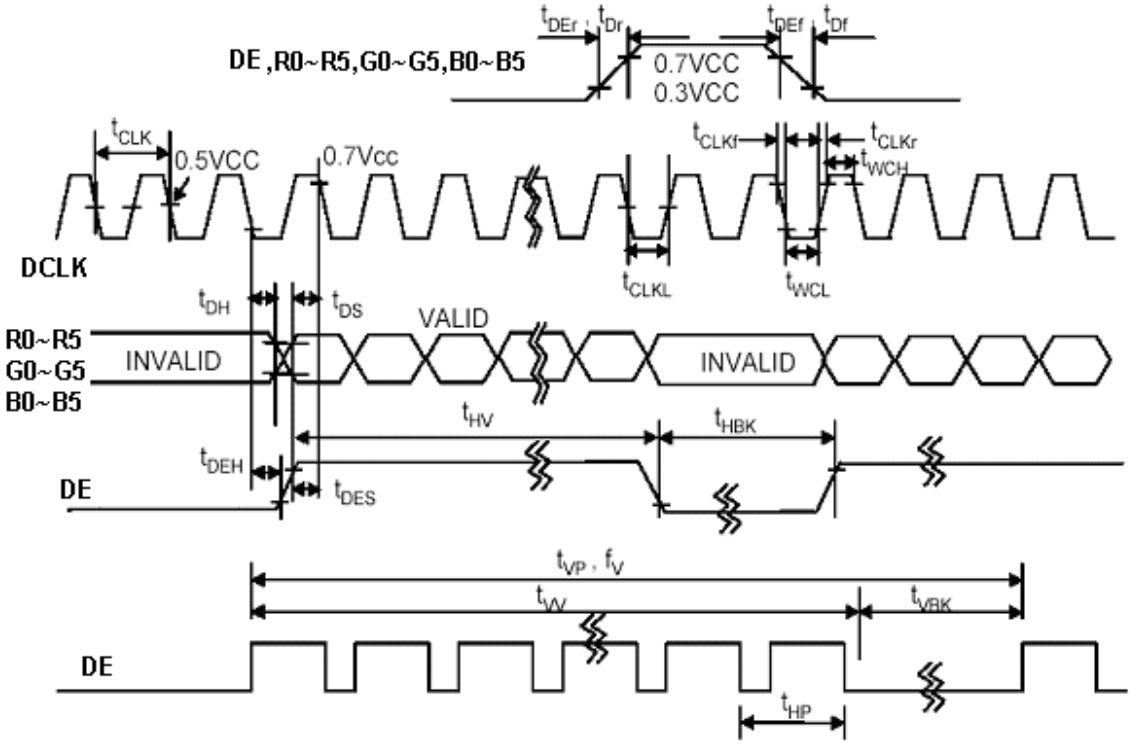
1. INTERFACE SPECIFICATIONS

1.1 DE mode Input signal characteristics

Signal	Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Remarks
DCLK	Period	t_{CLK}	33	40	43	ns	
	Frequency	f_{CLK}	23	25	30	MHz	
	Low Level Width	t_{WCL}	6	-	-	ns	
	High Level Width	t_{WCH}	6	-	-	ns	
	Rise, Fall Time	t_{CLKr}, t_{CLKf}	-	-	3	ns	
	Duty (1)	-	0.45	0.50	0.55	-	
DE (Data Enable)	Setup Time	t_{DES}	5	-	-	ns	
	Hold Time	t_{DEH}	10	-	-	ns	
	Rise, Fall Time	t_{DEr}, t_{DEf}	-	-	16	ns	
	Horizontal Period	t_{HP}	750	800	900	t_{CLK}	
	Horizontal Valid	t_{HV}	640	640	640	t_{CLK}	
	Horizontal Blank	t_{HBK}	110	160	260	t_{CLK}	
	Vertical Period	t_{VP}	515	525	560	t_{HP}	
	Vertical Valid	t_{W}	480	480	480	t_{HP}	
	Vertical Blank	t_{VBK}	35	45	80	t_{HP}	
	Vertical Frequency	f_{v}	55	60	65	Hz	
Data R,G,B	Setup Time	t_{DS}	5	-	-	ns	
	Hold Time	t_{DH}	10	-	-	ns	
	Rise, Fall Time	t_{Dr}, t_{Df}	-	-	3	ns	

Note: (1) tCLKL / tCLK.

1.1.1 DE mode timing waveform



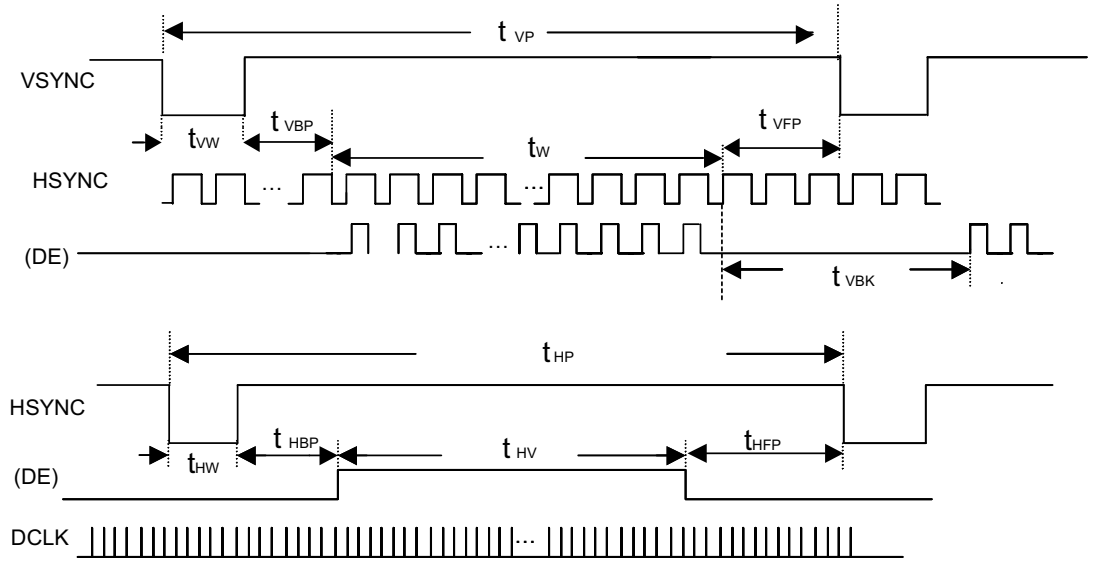
1.2 SYNC mode Input signal characteristics

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Remarks
Clock Period	t_{CLK}	33	40	43	ns	
Clock Frequency	f_{CLK}	23	25	30	MHz	
Clock Low Level Width	t_{WCL}	6	-	-	ns	
Clock High Level Width	t_{WCH}	6	-	-	ns	
Clock Rise, Fall Time	t_{CLKr}, t_{CLKf}	-	-	3	ns	
HSYNC Period	t_{HP}	750	800	900	t_{CLK}	
HSYNC Pulse Width	t_{HW}	5	30	-	t_{CLK}	
HSYNC Front Porch	t_{HFP}	1	16	116	t_{CLK}	
HSYNC Back Porch	t_{HBP}	1	114	139	t_{CLK}	
HSYNC Width + Back Porch	t_{HW}+ t_{HBP}	144	144	144	t_{CLK}	
Horizontal Blank	t_{HBK}	1	160	260	t_{CLK}	
Horizontal Valid	t_{HV}	640	640	640	t_{CLK}	
VSYNC Period	t_{VP}	515	525	560	t_{HP}	
VSYNC Pulse Width	t_{VW}	1	3	5	t_{HP}	
VSYNC Front Porch	t_{VFP}	1	10	45	t_{HP}	
VSYNC Back Porch	t_{VBP}	30	32	34	t_{HP}	
VSYNC Width + Back Porch	t_{VW}+ t_{VBP}	35	35	35	t_{CLK}	
Vertical Blank	t_{VBK}	35	45	80	t_{HP}	
Valid data Width	t_{W}	480	480	480	t_{HP}	
Data Setup Time	t_{DS}	5	-	-	ns	
Data Hold Time	t_{DH}	10	-	-	ns	

Note: (1) tHBK = tHFP + tHW + tHBP

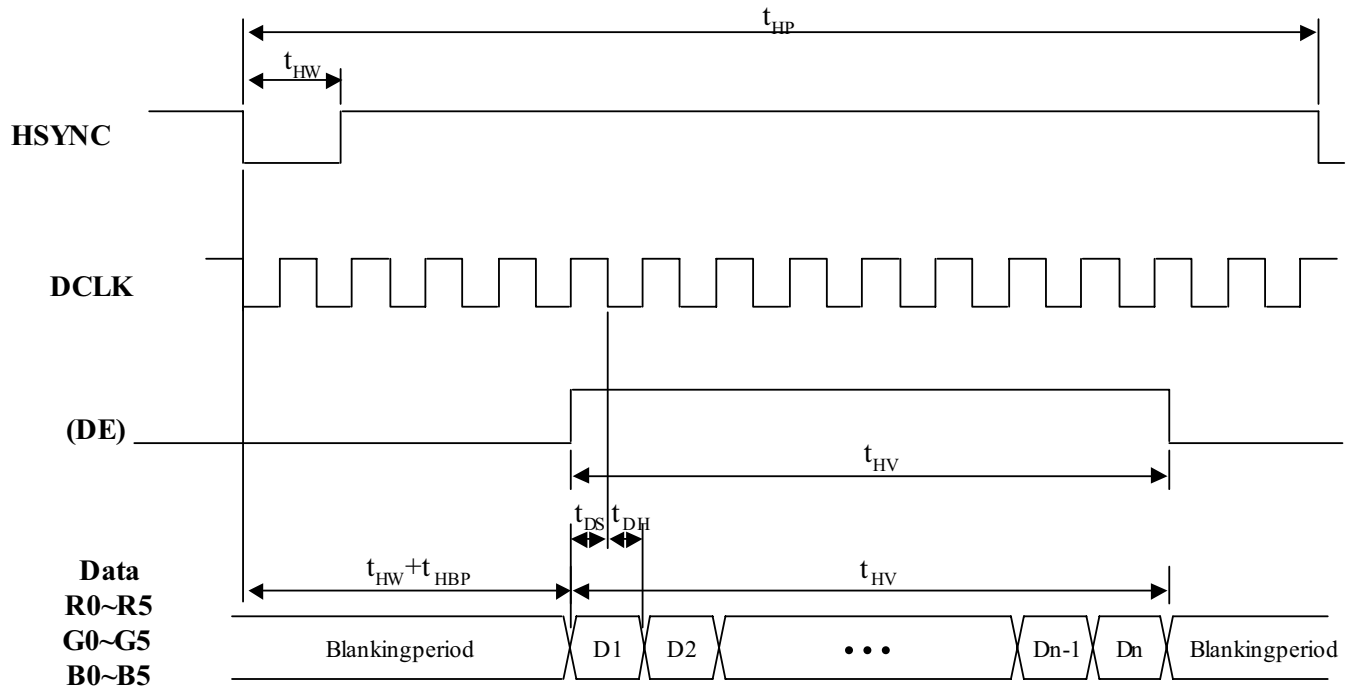
1.2.1 SYNC mode timing waveform

1.2.1.1 Input vertical timing



Remark : If SYNC mode is used, please fix DE signal to low, DE timing waveform is for reference only.

1.2.1.2 Input horizontal timing



Remark : If SYNC mode is used, please fix DE signal to low, DE timing waveform is for reference only.

1.3 Color Data Assignment

COLOR	INPUT	R DATA						G DATA						B DATA					
	DATA	R5	R4	R3	R2	R1	R0	G5	G4	G3	G2	G1	G0	B5	B4	B3	B2	B1	B0
		MSB					LSB	MSB					LSB	MSB					LSB
BASIC COLOR	BLACK	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	RED(63)	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0
	GREEN(63)	0	0	0	0	0	0	1	1	1	1	1	1	0	0	0	0	0	0
	BLUE(63)	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1
	CYAN	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1
	MAGENTA	1	1	1	1	1	1	0	0	0	0	0	0	1	1	1	1	1	1
	YELLOW	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0
	WHITE	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
RED	RED(0)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	RED(1)	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0
	RED(2)	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
	RED(62)	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0
	RED(63)	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0
GREEN	GREEN(0)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	GREEN(1)	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0
	GREEN(2)	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0
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	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
	GREEN(62)	0	0	0	0	0	0	1	1	1	1	1	0	0	0	0	0	0	0
	GREEN(63)	0	0	0	0	0	0	1	1	1	1	1	1	0	0	0	0	0	0
BLUE	BLUE(0)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	BLUE(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1
	BLUE(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0
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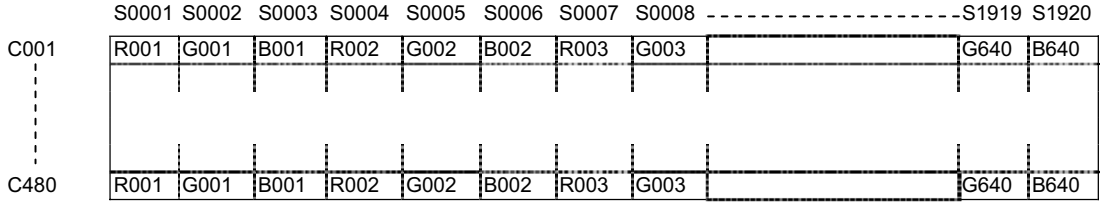
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
	BLUE(62)	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	0
	BLUE(63)	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1

Remarks:(1) Definition of Gray Scale
color(n):n is series of Gray Scale
The more n value is, the bright Gray Scale.
(2)Data:1-High,0-Low

Correspondence between Data and Display Position



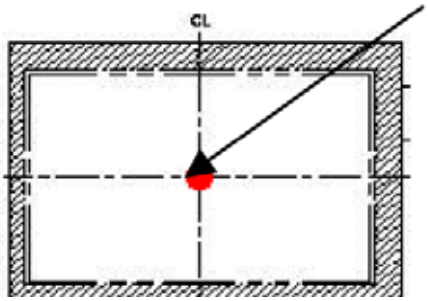
■ TOUCH SCREEN PANEL SPECIFICATIONS

1. CTP main feature

Item	Specification	Unit
Type	Transparent type projected capacitive touch panel	
Input mode	Human's finger	
Finger	5	
Sensor Active Area	118.76(W)(typ.) x 89.95(H)(typ.)	mm
Transparency	≧85%	%
Haze	≦5.0%	%
Hardness	7H (typ.) [by JIS K5400]	Pencil hardness
Report rate	Max：122	Points/sec
Response time	15	ms
Point hitting life time	1,000,000 times min.	Note 1

Note 1: Use 8 mm diameter silicon rubber/force 3N to knock on the same point twice per second (no-operating), after test function check pass.

central point



2. CTP Absolute Maximum Rating

Symbol	Description	Min	Typ.	Max	Unit	Notes
VCC1	Supply voltage	0.3	-	4	V	
VIO	DC input voltage	-0.3	-	VCC1+0.3	V	

3. CTP Electrical Characteristic

Symbol	Description	Min	Typ	Max	Unit	Notes
VCC1	Supply voltage	2.6	2.8	3.6	V	
GND	Supply voltage	-	0	-	V	
I	Active mode	-	10		mA	VCC1 = 2.8V
V_{IH}	Input H voltage	1.6	-	2.0	V	
V_{IL}	Input L voltage	-	-	0.7	V	
	System clock frequency	-	30	-	MHz	

4. CTP Pin Connections

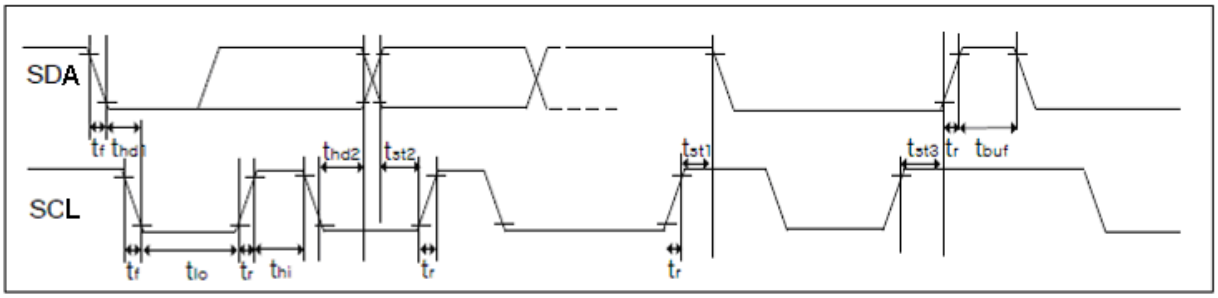
No.	Name	I/O	Description
1	NC	-	No connection
2	SCL	I	I^2C Clock
3	SDA	I/O	I^2C Data
4	NC	-	No connection
5	INT	O	Interrupt output
6	GND	P	Ground
7	VCC1	P	Power supply Voltage
8	/RESET	I	Reset active low
9	NC	-	No connection

5. CTP Interface and Data Format [Slave address is 0x5D（7 bit addressing）]

Communication protocol: I^2C

Clock frequency : 100Khz （400Khz Fast mode）

Below is timing of I2C hardware circuit:



Parameter	Symbol	Min	Max	Unit
SCL frequency	f_{sck}	-	600	KHZ
SCL low period	t_{lo}	0.8	-	us
SCL high period	t_{hi}	0.5	-	us
SCL setup time for START condition	t_{st1}	0.4	-	us
SCL setup time for STOP condition	t_{st3}	0.4	-	us
SCL hold time for START condition	t_{st1}	0.4	-	us
SDA setup time	t_{st2}	0.5	-	us
SDA hold time	t_{st2}	0.2	-	us

6. Timing Characteristic

The address of GT927's slave device is 0xBA/0xBB. When master CPU addressing GT927, it will send read and write control bits simultaneously where are appended to slave device ("0"- write; "1"- read) for composing a byte with device address. i.e.: 0xBA – conduct write operation to GT927; 0xBB – conduct read operation to GT927.

6.1 Postfix Communication:

Only after receiving postfix signal (under the condition of no external signal), can GT927 update coordinate in buffer in real time. After completing communication, I2C needs to send extra postfix signal. But if a series of communication appear, the postfix signal should be sent after the last one finished (except the coordinate reading process, the postfix signal could be sent after finishing reading a frame, so as to prevent output buffer to be changed by GT927 during the read process of master device). Below is the communication format of postfix: Use write process to search register addressing (0x8000), and send stop signal.

6.2 Data Transmission:

The communication usually is launched by master CPU. When SCL keeps “1” SDA manages the change from “1” to “0”. Then the address information or data stream begins to transmit after start signal.
Any slave device connected with I2C circuit needs to check 8 bits address information after circuit launches start signal and respond correctly. After receiving the matching address information, GT927 will update SDA as an output and set the value as “0” for answering signal in the ninth clock cycle. The GT927 will lay idle if matching address information is unavailable (neither 0XBA nor 0XBB).
The SDA port sends the data with 9 bits serial data according to nine clock cycles. The 8 valid data + 1 receiver send ACK (acknowledgement signal) or NACK (negative acknowledgement signal). It is valid when SCL is “1” during the data transmission.
The main CPU sends stop signal after transmission where SDA manages the change from “0” to “1” when SCL stays “1”.

6.3 Write operations to I²C slave

Write operations

Above is the flow chart of master CPU conducting write process for GT927. Master CPU launches a start signal and sends address, write and read information (“0” means write process -- 0XBA).

After receiving response，master CPU sends 16 bits address of register and writes 8 bits into register

The address pointer of GT927’s register will automatically increase 1 in write process. So it can continuously write continuation register address at a time. If write process is done, master CPU sends stop signal.

6.4 Read operations to I²C slave

Read operation

Above is the flow chart of master CPU conducting read process for GT927. Master CPU launches a start signal and sends address, write and read information ("0" means read process -- 0XAA).

Once receives acknowledgement signal, master CPU sends 16 bits register address information and sets the read-demanding register address. Then master CPU resends a start signal for read process (0XAB). It begins to read data until receiving acknowledge.

Likewise, GT927 can conduct continuation read process. Master CPU will correspondingly send an acknowledgement signal to indicate successful byte reception. And CPU will send "NACK" once receiving the last byte to stop transmission.

7 Register information

Addr	R/W	Name	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0
0XF40	R	Touch Flags	Buffer Status		L_touch	P4	P3	P2	P1	P0
0XF41	R	Touch key	Reserved				Key4	Key3	Key2	Key1
0XF42	R	Point0	Point0 X H							
0XF43	R		Point0 X L							
0XF44	R		Point0 Y H							
0XF45	R		Point0 Y L							
0XF46	R	Point1	Point0 Size							
0XF47	R		Point1 X H							
0XF48	R		Point1 X L							
0XF49	R		Point1 Y H							
0XF4A	R		Point1 Y L							
0XF4B	R		Point1 Size							
0XF4C	R	Point2	Point2 X H							
0XF4D	R		Point2 X L							
0XF4E	R		Point2 Y H							
0XF4F	R		Point2 Y L							
0XF50	R		Point2 Size							
0XF51	R	Point3	Point3 X H							
0XF52	R		Point3 X L							
0XF53	R		Point3 Y H							
0XF54	R		Point3 Y L							
0XF55	R		Point3 Size							
0XF56	R	Point4	Point4 X H							
0XF57	R		Point4 X L							
0XF58	R		Point4 Y H							
0XF59	R		Point4 Y L							
0XF5A	R		Point4 Size							
0XF5B	R	Coor checksum	Coordinate checksum							
0XF5C~ 0XF7C	-	NC	Reserved							
0xF7D	R	PID	Product ID(hex)							

0xF7E	R	VID_H	Product version High byte(hex)
0xF7F	R	VID_L	Product version low byte(hex)
0xF80	R/W	DriverCH0	Screen 1 drives corresponding IC drive line
0xF81	R/W	DriverCH1	Screen 2 drives corresponding IC drive line
0xF82	R/W	DriverCH2	Screen 3 drives corresponding IC drive line
0xF83	R/W	DriverCH3	Screen 4 drives corresponding IC drive line
0xF84	R/W	DriverCH4	Screen 5 drives corresponding IC drive line
0xF85	R/W	DriverCH5	Screen 6 drives corresponding IC drive line
0xF86	R/W	DriverCH6	Screen 7 drives corresponding IC drive line
0xF87	R/W	DriverCH7	Screen 8 drives corresponding IC drive line
0xF88	R/W	DriverCH8	Screen 9 drives corresponding IC drive line
0xF89	R/W	DriverCH9	Screen 10 drives corresponding IC drive line
0xF8A	R/W	DriverCH10	Screen 11 drives corresponding IC drive line
0xF8B	R/W	DriverCH11	Screen 12 drives corresponding IC drive line
0xF8C	R/W	DriverCH12	Screen 13 drives corresponding IC drive line
0xF8D	R/W	DriverCH13	Screen 14 drives corresponding IC drive line
0xF8E	R/W	DriverCH14	Screen 15 drives corresponding IC drive line
0xF8F	R/W	DriverCH15	Screen 16 drives corresponding IC drive line
0xF90	R/W	DriverCH16	Screen 17 drives corresponding IC drive line
0xF91	R/W	DriverCH17	Screen 18 drives corresponding IC drive line
0xF92	R/W	DriverCH18	Screen 19 drives corresponding IC drive line
0xF93	R/W	DriverCH19	Screen 20 drives corresponding IC drive line
0xF94	R/W	DriverCH20	Screen 21 drives corresponding IC drive line
0xF95	R/W	DriverCH21	Screen 22 drives corresponding IC drive line
0xF96	R/W	DriverCH22	Screen 23 drives corresponding IC drive line
0xF97	R/W	DriverCH23	Screen 24 drives corresponding IC drive line
0xF98	R/W	DriverCH24	Screen 25 drives corresponding IC drive line
0xF99	R/W	DriverCH25	Screen 26 drives corresponding IC drive line
0xF9A	R/W	DriverCH26	Screen 27 drives corresponding IC drive line
0xF9B	R/W	DriverCH27	Screen 28 drives corresponding IC drive line
0xF9C	R/W	DriverCH28	Screen 29 drives corresponding IC drive line
0xF9D	R/W	NC	Reserved
0xF9E	R/W	SensorCH0	Screen 1 induction wire corresponds to IC drive line
0xF9F	R/W	SensorCH1	Screen 2 induction wire corresponds to IC drive line
0xFA0	R/W	SensorCH2	Screen 3 induction wire corresponds to IC drive line
0xFA1	R/W	SensorCH3	Screen 4 induction wire corresponds to IC drive line
0xFA2	R/W	SensorCH4	Screen 5 induction wire corresponds to IC drive line
0xFA3	R/W	SensorCH5	Screen 6 induction wire corresponds to IC drive line
0xFA4	R/W	SensorCH6	Screen 7 induction wire corresponds to IC drive line
0xFA5	R/W	SensorCH7	Screen 8 induction wire corresponds to IC drive line
0xFA6	R/W	SensorCH8	Screen 9 induction wire corresponds to IC drive line
0xFA7	R/W	SensorCH9	Screen 10 induction wire corresponds to IC drive line
0xFA8	R/W	SensorCH10	Screen 11 induction wire corresponds to IC drive line
0xFA9	R/W	SensorCH11	Screen 12 induction wire corresponds to IC drive line
0xFAA	R/W	SensorCH12	Screen 13 induction wire corresponds to IC drive line
0xFAB	R/W	SensorCH13	Screen 14 induction wire corresponds to IC drive line
0XFAC	R/W	SensorCH13	Screen 15 induction wire corresponds to IC drive line
0XFAD	R/W	SensorCH14	Screen 16 induction wire corresponds to IC drive line
0XFAE~ 0XFB1	-	NC	Reserved
0xFB2	R/W	ADCCFG	chip scanning control parameter
0xFB3	R/W	SCAN	chip scanning control parameter
0xFB4	R/W	F1SET	drive pulse 1 frequency

0xFB5	R/W	F2SET	drive pulse 2 frequency							
0xFB6	R/W	F3SET	drive pulse 3 frequency							
0xFB7	R/W	F1PNUM	1 drive pulse							
0xFB8	R/W	F2PNUM	2 drive pulse							
0xFB9	R/W	F3PNUM	3 drive puilse							
0xFBA	R/W	F1DELAY	drive pulse 1 phase delay							
0xFBB	R/W	F2DELAY	drive pulse 2 phase delay							
0xFBC	R/W	F3DELAY	drive pulse 3 phase delay							
0xFBD	R/W	DC-DC	high pressure setting							
0xFBE	R/W	Sc_Touch	TP key threshold							
0xFBF	R/W	Sc_Leave	TP key up threshold							
0xFC0	R/W	Md_switch	Reserved	DD2: difference And half	Reserved	Shape_EN defamation denoise	INT pulse mode	SITO denoise switch	Reserved	Reserved
0xFC1	R/W	LPower_C	Reserved	time to low power consumption without pressing: 0-63s valid, unit: S						
0xFC2	R/W	Refresh	0-100 valid; 0: period 10ms, 100: period 20ms							
0xFC3	R/W	Touch_N	Reserved	Reserved	Output touch point, 1-5 valid					
0xFC4	R/W	Output_Th	output limit: output until coordinate transformation value is higher than this, 0-254 configurable (unit:4 coordinate),255 means first pressing coordinate and keying up							
0xFC5	R/W	X_Ou_Max_H	X direction output maximum coordinate, the higher byte placed first							
0xFC6	R/W	X_Ou_Max_L								
0xFC7	R/W	Y_Ou_Max_H	Y direction output maximum coordinate, the higher byte placed first							
0xFC8	R/W	Y_Ou_Max_L								
0xFC9	R/W	X_Co_Sm	X direction slide control parameter, 0-255 configurable, 0 means closure							
0xFCA	R/W	Y_Co_Sm	Y direction slide control parameter, 0-255 configurable, 0 means closure							
0xFCB	R/W	X_Sp_Lim	X direction maximum speed limit of slide: 0-255 configurable, 0 means closure(unit:16 coordinate)							
0xFCC	R/W	Y_Sp_Lim	Y direction maximum speed limit of slide: 0-255 configurable, 0 means closure(unit:16 coordinate)							
0xFCD	R/W	Noise_R	sampling drop-driven					while noise elimination: 0-15 valid		
0xFCE	R/W	NC	Reserved							
0xFCF	R/W	Filter	Reserved					coordinate window filtering value (in base 4)		
0xFD0	R/W	Large_Tc	representative touch points for large area: 0-255 valid							
0xFD1	R/W	Shake_Cu	Touch Shake Count					Finger Number Shake Count		
0xFD2	R/W	Pos_Ref_T	benchmark update configuration in normal condition, 0-255 valid, 0 means close benchmark update							
0xFD3	R/W	NC	benchmark update configuration in sudden change condition,0-255 valid, 0 means close benchmark update							
0xFD4	R/W	NC	Reserved							
0xFD5	R/W	NC								
0xFD6	R/W	Edge_exp	Reserved					0: weak tensile 1: strong		
0xFD7	R/W	Tc_K_F	Key_com	Key_con	Reserved			valid interval in regional keys (unilateral): 0-15 valid		
0xFD8	R/W	Key 1	Key 1 position: 0-255 valid, 0 means unavailable							
0xFD9	R/W	Key 2	Key 2 position: 0-255 valid, 0 means unavailable							
0xFDA	R/W	Key 3	Key 3 position: 0-255 valid, 0 means unavailable							
0xFDB	R/W	Key 4	Key 4 position: 0-255 valid, 0 means unavailable							
0xFDC	R/W	K_Touch	key threshold							
0xFDD	R/W	K_Leave	key up threshold							
0xFDE	R/W	K_SEC_max	upper limit of sub-maximum difference in independent key judgment							
0xFEF	R/W	K_DIS_min	lower limit of difference between maximum and sub-maximum in independent key judgment							
0xFE0	R/W	X_border_Lim_	discarded coordinate numbers on X proximal border							

		Near				
0xFE1	R/W	X_border_Lim_Far	discarded coordinate numbers on X far end			
0xFE2	R/W	Y_border_Lim_Near	discarded coordinate numbers on Y proximal border			
0xFE3	R/W	Y_border_Lim_Far	discarded coordinate numbers on Y far end			
0xFE4	R/W	KEY_ADCCFG	FPC ADCCFG parameter (applicable to drive key common port)			
0xFE5	R/W	KEY_F1SET	FPC drive frequency setting (applicable to drive key common port)			
0xFE6	R/W	KEY_F1NUM	FPC drive pulse number setting (applicable to drive key common port)			
0xFE7	R/W	Key_Shake_Cu	touch key Shake counter (0-255)			
0xFE8	R/W	Key2_Touch	touch Level of FPC touch key2			
0xFE9	R/W	Key3_Touch	touch Level of FPC touch key3			
0xFEA	R/W	Key4_Touch	touch Level of FPC touch key4			
0xFEB~0xFEE	-	NC	Reserved			
0xFEF	R/W	Con_Frs	mark for configuration update, write 1 when master completing configuration information			
0xFF0	R/W	Cfg_Chk_H	configuration information checksum, the higher byte placed first			
0xFF1	R/W	Cfg_Chk_L				
0xFF2	R/W	System_Sta	Power_sta		Reserved	
0xFF3	R/W	LED_Con	LED_EN	LED_CM	LED_SW	time of light-on after key up (unit: S)
0xFF4	R/W	Command	Reserved			
0xFF5	R/W	Module_Type	Reserved			module supplier' ID: 0-2 valid

■ RELIABILITY TEST

No.	Test Item	Test Condition
1	High Temperature Storage	70±2℃/120 hours
2	Low Temperature Storage	-20±2℃/120 hours
3	High Temperature Operating	60±2℃/120 hours
4	Low Temperature Operating	-10±2℃/120 hours
5	Temperature Cycle storage	-30±2℃~25~80±2℃×200cycles (30min.) (5min.) (30min.)
6	Damp proof Test operating	40℃±5℃×90%RH/120 hours
7	Vibration Test (no-operation)	Frequency：0~55Hz Amplitude:1.5mm Sweep time: 11min 6 cycles for each direction of X.Y.Z
8	ESD test (No operation)	Air:±15KV;Contact:±8KV

■ INSPECTION CRITERION

OUTGOING QUALITY STANDARD	PAGE 1 OF 8
TITLE:FUNCTIONAL TEST & INSPECTION CRITERIA	

This specification is made to be used as the standard acceptance/rejection criteria for Wider Screen TFT-LCD module product.

1. Sample plan

Sampling plan according to GB/T2828.1-2003/ISO 2859-1： 1999 and ANSI/ASQC Z1.4-1993, normal level 2 and based on:

Major defect: AQL 0.65

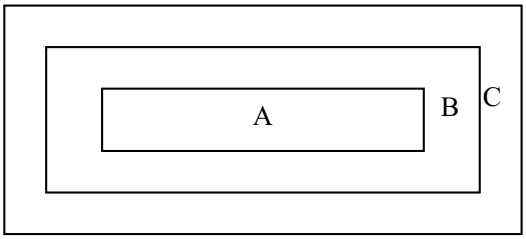
Minor defect: AQL 1.5

2. Inspection condition

Viewing distance for cosmetic inspection is about 30cm with bare eyes, and under an environment of 20~40W light intensity, all directions for inspecting the sample should be within 45° against perpendicular line.

3. Definition of Inspection Item.

3.1 Definition of inspection zone in LCD.



Zone A: character/Digit area

Zone B: viewing area except Zone A (ZoneA+ZoneB=minimum Viewing area)

Zone C: Outside viewing area (invisible area after assembly in customer's product)

ZoneB+ZoneC= Around opaque edge area on TP.

Fig.1 Inspection zones in an LCD.

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for quality and assembly of customer's product.

3.2 Definition of some visual defect

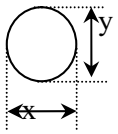
Bright dot.	Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern.
Dark dot.	Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue picture, or pure whiter picture.
Dark / Bright Lines.	Lines on display which appear dark/bright and usually result from the contamination.

OUTGOING QUALITY STANDARD	PAGE 2 OF 8
TITLE:FUNCTIONAL TEST & INSPECTION CRITERIA	

4. Major Defect

Item No	Items to be inspected	Inspection Standard	Classification of defects
4.1	All functional defects	1) No display 2) Display abnormally 3) Open or missing segment 4) Short circuit 5) Excess power consumption 6) Back-light no lighting, flickering and abnormal lighting.	Major
4.2	Missing	Missing component	
4.3	Outline dimension	Overall outline dimension beyond the drawing is not allowed.	
4.4	Crack	Creaks tend to break are not allowed.	

5. Minor Defect

Item No	Items to be inspected	Inspection Standard	Classification of defects
5.1	Bright dot. defect.  Φ=(x+y) /2	Zone / Size(mm) | Acceptable Qty: A | B | C Φ≤0.15 | Acceptable (clustering of spot not allowed) | Acceptable 0.15<Φ≤0.25 | N≤6. 0.25<Φ≤0.50 | N≤2	Minor
5.2	Dark dot defect.	Zone / Size(mm) | Acceptable Q'ty: A | B | C Φ≤0.15 | Acceptable | Acceptable 0.15<Φ≤0.30 | N≤6 0.30<Φ≤0.50 | N≤4	
5.3	Bright / Dark line.	0.01 < W ≤ 0.10, 0.30 < L ≤ 1.50, N≤1	Acceptable

Note: 1. Total defective dots shall not exceed 6 pcs.
2. Minimum distance between defective dots is more than 5mm.
3. 2 Adjacent dark sub pixel defect or bright sub pixel defect is not more than 1pair.
4. W: Width, L: Length, N: Count.

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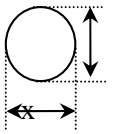
TITLE:FUNCTIONAL TEST & INSPECTION CRITERIA

<table>
<tr><th>Item No</th><th>Items to be inspected</th><th>Inspection Standard</th><th>Classification of defects</th></tr>
<tr><td rowspan="2">5.4</td><td>Linear defect
Foreign material under polarizer,</td><td>
<table>
<tr><th colspan="2">Size(m)</th><th colspan="3">Acceptable Qty</th></tr>
<tr><th rowspan="2">L(Length)</th><th rowspan="2">W(Width)</th><th colspan="3">Zone</th></tr>
<tr><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Ignore</td><td>W≤0.05</td><td colspan="2">Acceptable</td><td rowspan="3">Acceptable</td></tr>
<tr><td>L≤5.0</td><td>0.05＜W≤0.15</td><td colspan="2">N≤5</td></tr>
<tr><td>5.0≤L</td><td>0.15≤W</td><td colspan="2">0</td></tr>
</table>
</td><td>Minor</td></tr>
<tr><td>Circular Defect,
Foreign material under polarizer,
 

Φ=(x+y) /2</td><td>
<table>
<tr><th>Zone
Size(mm)</th><th colspan="3">Acceptable Q’ty</th></tr>
<tr><th></th><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Φ≤0.25</td><td colspan="2">Acceptable</td><td rowspan="3">Acceptable</td></tr>
<tr><td>0.25＜Φ≤0.50</td><td colspan="2">N≤4</td></tr>
<tr><td>0.50≤Φ</td><td colspan="2">0</td></tr>
</table>
</td><td>Minor</td></tr>
<tr><td>5.5</td><td>Polarizer defect.</td><td>5.4.1 Polarizer Position
(i) Shifting in position should not exceed the glass outline dimension.
(ii) Incomplete covering of the viewing area due to shifting is not allowed.
5.4.2 Dirt on polarizer
Dirt which can be wiped easily should be accepted.
5.4.3 Polarizer Nick & Dent
<table>
<tr><th rowspan="3">Sizes(mm)</th><th colspan="3">Acceptable Qty</th></tr>
<tr><th colspan="3">Zone</th></tr>
<tr><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Φ＜0.25</td><td colspan="2">Acceptable</td><td rowspan="3">Acceptable</td></tr>
<tr><td>0.25≤Φ≤0.5</td><td colspan="2">N≤4</td></tr>
<tr><td>Φ＞0.5</td><td colspan="2">0</td></tr>
</table>
</td><td>Minor</td></tr>
</table>

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5. Minor Defect

<table>
<tr><th>Item No</th><th>Items to be inspected</th><th>Inspection Standard</th><th>Classification of defects</th></tr>
<tr><td rowspan="2">5.6</td><td rowspan="2">Polarizer defect</td><td>5.4.4Air bubbles between glass & polarizer:
<table>
<tr><td rowspan="3">Size(mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td colspan="3">Zone</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Φ≤0.3</td><td colspan="2">Acceptable</td><td rowspan="4">Acceptable</td></tr>
<tr><td>0.3＜Φ≤1.0</td><td colspan="2">3</td></tr>
<tr><td>1.0＜Φ≤1.5</td><td colspan="2">1</td></tr>
<tr><td>Φ＞1.5</td><td colspan="2">0</td></tr>
</table></td><td>Minor</td></tr>
<tr><td>5.4.5 Polarizer scratch
(i) If the Polarizer scratch can be seen after cover assembling or in the operating condition, judge by the line defect of 5.4.
(ii) If the Polarizer scratch can be seen only in non-operating condition or some special angle, judge by the following.
<table>
<tr><td colspan="2">Size(mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td rowspan="2">L(Length)</td><td rowspan="2">W(Width)</td><td colspan="3">Zone</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Ignore</td><td>W≤0.02</td><td colspan="2">Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>1.0＜L≤5.0</td><td>0.02＜W≤0.2</td><td colspan="2">N≤4.</td></tr>
<tr><td>5.0＜L</td><td>0.2＜W</td><td colspan="2">0</td></tr>
</table></td><td>Minor</td></tr>
</table>

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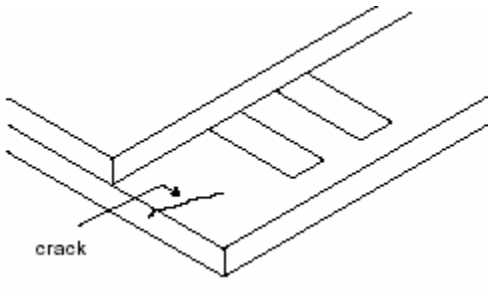
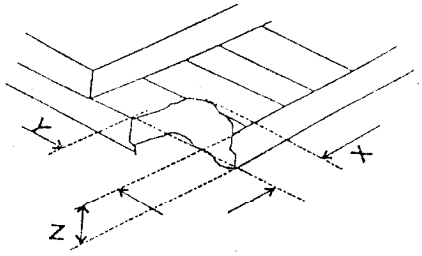
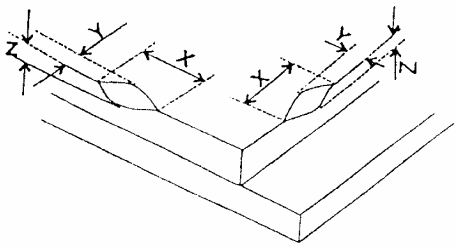
5. Minor Defect

<table>
<tr><th>Item No</th><th>Items to be inspected</th><th>Inspection Standard</th><th>Classification of defects</th></tr>
<tr><td rowspan="3">5.7</td><td rowspan="3">Glass defect</td><td>(i) Crack
Cracks are not allowed.
 
</td><td>Minor</td></tr>
<tr><td>(ii) TFT chips on corner
 

<table><tr><th>X</th><th>Y</th><th>Z</th><th>Acceptable</th></tr><tr><td>≤3.0</td><td>≤3.0</td><td>Not more than the thickness of glass.</td><td>N≤3.</td></tr></table>Chips on the corner of terminal shall not be allowed to extend into the ITO pad or expose perimeter seal.</td><td>Minor</td></tr>
<tr><td>(iii)Usual surface cracks
 

<table><tr><th>X</th><th>Y</th><th>Z</th><th>Acceptable</th></tr><tr><td>≤1.5</td><td>≤1.5</td><td>Not more than the thickness of glass.</td><td>N≤4.</td></tr></table>It is only applicable to the upper glass of LCD.</td><td>Minor</td></tr>
</table>

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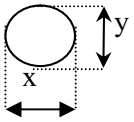
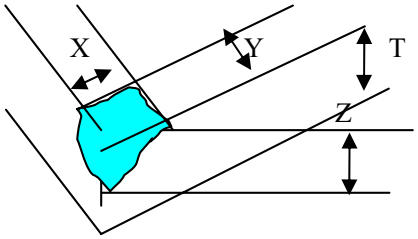
6. TP Cosmetic Defect.

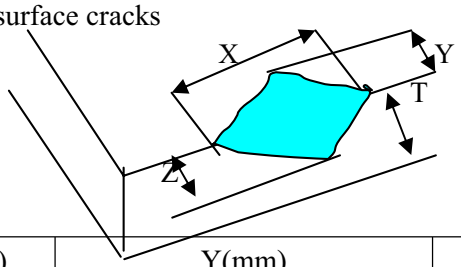
<table>
<tr><th>Item No</th><th>Items to be inspected</th><th>Inspection Standard</th><th>Classification of defects</th></tr>
<tr><td>6.1</td><td>Black and white Spot defect Foreign Particle,</td><td>For dark/white spot, size Φ is defined as $\Phi = \frac{(x+y)}{2}$ 

<table>
<tr><th rowspan="2">Zone
Size(mm)</th><th colspan="3">Acceptable Qty</th></tr>
<tr><th>A</th><th>B+C</th><th></th></tr>
<tr><td>Φ≤0.15</td><td colspan="2">Ignore</td><td rowspan="4">distance 5mm over</td></tr>
<tr><td>0.15＜Φ≤0.25</td><td colspan="2">6</td></tr>
<tr><td>0.25＜Φ≤0.50</td><td colspan="2">4</td></tr>
<tr><td>Φ＞0.5</td><td colspan="2">0</td></tr>
<tr><td colspan="4">Total defective dots shall not exceed 6 pcs on the same TP.</td></tr>
</table></td><td>Minor</td></tr>
<tr><th>Item No</th><th>Items to be inspected</th><th>Inspection Standard</th><th>Classification of defects</th></tr>
<tr><td>6.2</td><td>Black line, White line, Scratch, Foreign material under film,</td><td>
<table>
<tr><th colspan="2">Size(mm)</th><th colspan="3">Acceptable Qty</th></tr>
<tr><th rowspan="2">L(Length)</th><th rowspan="2">W(Width)</th><th colspan="3">Zone</th></tr>
<tr><th>A</th><th>B+C</th><th></th></tr>
<tr><td>Ignore</td><td>W≤0.03</td><td colspan="2">Ignore</td><td rowspan="4">distance 5mm over</td></tr>
<tr><td>L≤5.0</td><td>0.03＜W≤0.05</td><td colspan="2">5</td></tr>
<tr><td>L≤5.0</td><td>0.05＜W≤0.1</td><td colspan="2">2</td></tr>
<tr><td></td><td>0.1＜W</td><td colspan="2">0</td></tr>
</table></td><td>Minor</td></tr>
</table>

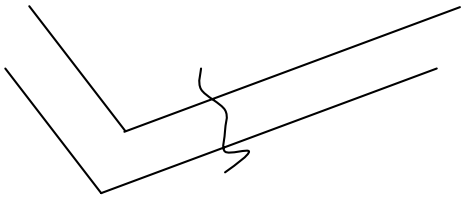
OUTGOING QUALITY STANDARD	PAGE 7 OF 8
TITLE:FUNCTIONAL TEST & INSPECTION CRITERIA	

6. TP Cosmetic Defect

<table>
<tr><th>Item No</th><th>Items to be inspected</th><th>Inspection Standard</th><th>Classification of defects</th></tr>
<tr><td rowspan="2">6.3</td><td rowspan="2">TP defect
,</td><td>(i) Chips on corner
 

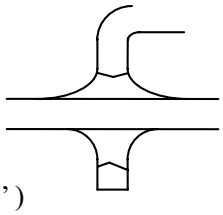
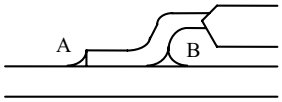
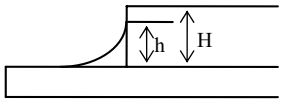
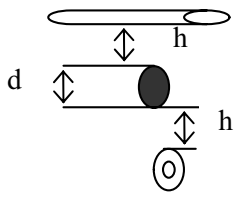
<table><tr><th>X(mm)</th><th>Y(mm)</th><th>Z(mm)</th></tr><tr><td>≤3.0</td><td>≤3.0</td><td>Z<T</td></tr></table>
(ii)Usual surface cracks
 

<table><tr><th>X(mm)</th><th>Y(mm)</th><th>Z(mm)</th></tr><tr><td>≤6.0</td><td><2.0</td><td>Z<T</td></tr></table></td><td>Minor

Minor</td></tr>
<tr><td>(iii) Crack
Cracks tending to break are not allowed.
  </td><td>Major</td></tr>
<tr><td>6.4</td><td>Total number of dots</td><td>The total number of luminous dots, dark dots, contamination particles, bubbles, scratch defects, pinholes must not exceed 10 /piece on the same TP.</td><td></td></tr>
</table>

OUTGOING QUALITY STANDARD	PAGE 8 OF 8
TITLE:FUNCTIONAL TEST & INSPECTION CRITERIA	

7. **Module Cosmetic Criteria**

Item No	Items to be inspected	Inspection Standard	Classification of defects
1	Difference in Spec.	None allowed	Major
2	Pattern peeling	No substrate pattern peeling and floating	Major
3	Soldering defects	No soldering missing No soldering bridge No cold soldering	Major Major Minor
4	Resist flaw on Printed Circuit Boards	visible copper foil (∅0.5mm or more) on substrate pattern.	Minor
5	Accretion of metallic Foreign matter	No accretion of metallic foreign matters (Not exceed ∅0.2mm).	Minor Minor
6	Stain	No stain to spoil cosmetic badly.	Minor
7	Plate discoloring	No plate fading, rusting and discoloring.	Minor
8	Solder amount 1. Lead parts	a. Soldering side of PCB Solder to form a 'Filet' all around the lead. Solder should not hide the lead form perfectly. (too much) b. Components side (In case of 'Through Hole PCB') Solder to reach the Components side of PCB. 	Minor
	2. Flat packages	Either 'Toe' (A) or 'Seal' (B) of the lead to be covered by 'Filet'. Lead form to be assume over solder. 	Minor
	3. Chips	(3/2) H ≥ h ≥ (1/2) H 	Minor
9	Solder ball/Solder splash	a.The spacing between solder ball and the conductor or solder pad h ≥0.13mm.The diameter of solder ball d ≤0.15mm.  b.The quantity of solder balls or solder. Splashes isn't beyond 5 in 600 mm ^{2} . c.Solder balls/Solder splashes do not violate minimum electrical clearance. d.Solder balls/Solder splashes must be entrapped / encapsulated or attached to the metal surface . Note: Entrapped/encapsulated/attached is intended to mean that normal service environment of the product will not cause a solder ball to become dislodged.	Minor Minor Major Minor

■ PRECAUTIONS FOR USING LCD MODULES

Handing Precautions

(1) The display panel is made of glass and polarizer. As glass is fragile. It tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.

(2) If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.

(3) Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degraded insulation between terminals (some cosmetics are determined to the polarizer).

(4) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming is contacting with room temperature air.

(5) If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents

- Isopropyl alcohol
- Ethyl alcohol

Do not scrub hard to avoid damaging the display surface.

(6) Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.

- Water
- Ketone
- Aromatic solvents

Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contacting oil and fats.

(7) Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.

(8) Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.

(9) Do not attempt to disassemble or process the LCD module.

(10) NC terminal should be open. Do not connect anything.

(11) If the logic circuit power is off, do not apply the input signals.

(12) Electro-Static Discharge Control, Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

- Before remove LCM from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential. Be sure to ground the body when handling the LCD modules.
- Tools required for assembling, such as soldering irons, must be properly grounded. make certain the AC power source for the soldering iron does not leak. When using an electric screwdriver to attach LCM, the screwdriver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.
- To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions. To reduce the generation of static electricity be careful that the air in the work is not too dried. A relative humidity of 50%-60% is recommended. As far as possible make the electric potential of your work clothes and that of the work bench the ground potential
- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated

（13）Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.

- Do not alter, modify or change the shape of the tab on the metal frame.
- Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
- Do not damage or modify the pattern writing on the printed circuit board.
- Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
- Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- Do not drop, bend or twist LCM.

Storage Precautions

When storing the LCD modules, the following precaution is necessary.

(1) Store them in a sealed polyethylene bag. If properly sealed, there is no need for the dessicant.

(2) Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C.

(3) The polarizer surface should not come in contact with any other objects. (We advise you to store them in the container in which they were shipped).

Others

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

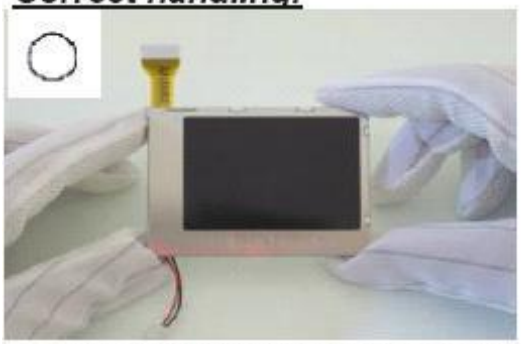
To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

- Exposed area of the printed circuit board.
-Terminal electrode sections.

Handling precaution for LCM

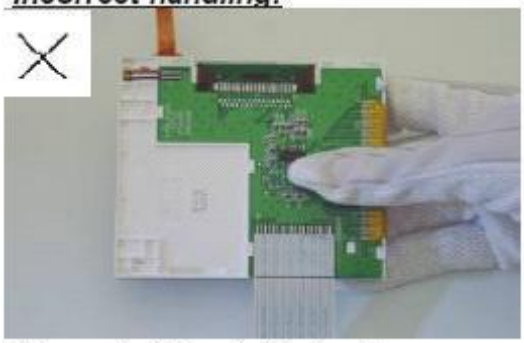
LCM is easy to be damaged.
Please note below and be careful for handling!

Correct handling:

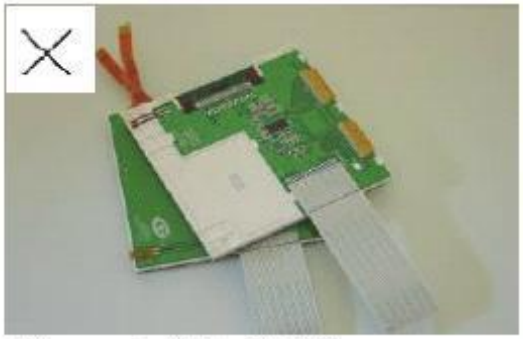


As above picture, please handle with anti-static gloves around LCM edges.

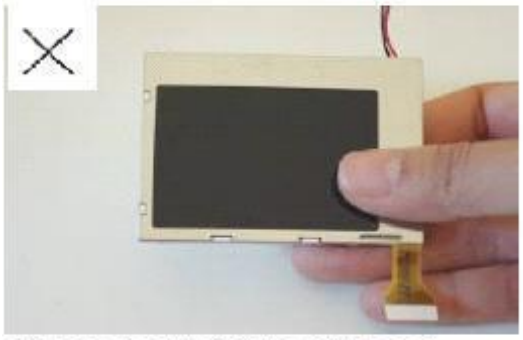
Incorrect handling:



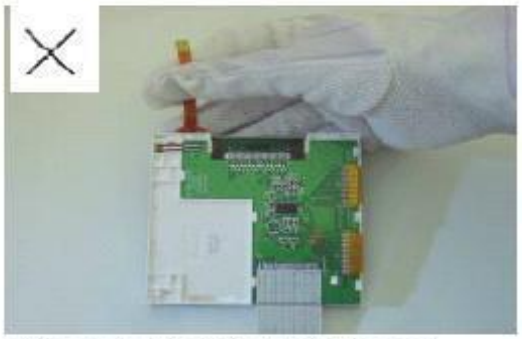
Please don't touch IC directly.



Please don't stack LCM.



Please don't hold the surface of panel.

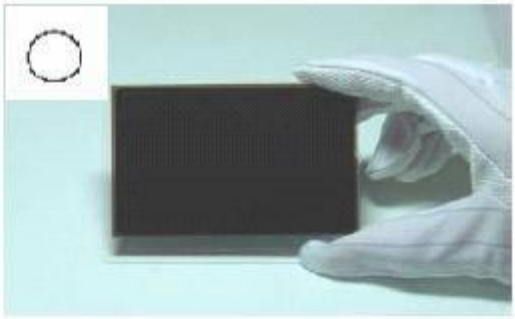


Please don't stretch interface of output, such as FPC cable.

Handling precaution for LCD

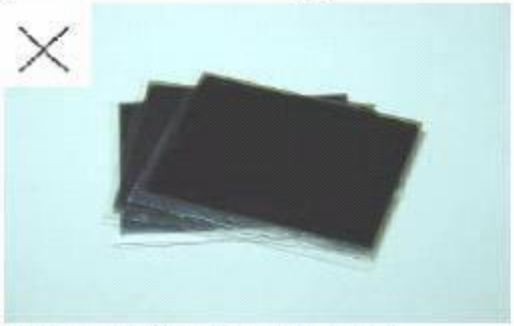
LCD is easy to be damaged.
Please note below and be careful for handling!

Correct handling:



As above photo, please handle with anti-static gloves around LCD edges.

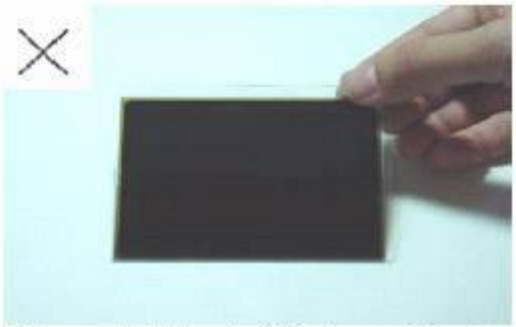
Incorrect handling:



Please don't stack the LCDS.

Please don't hold the surface of LCD.

Please don't operate with sharp stick such as pens.



Please don't touch ITO glass without anti-static gloves.

Storage Precautions

When storing the LCD modules, the following precaution is necessary.

(1) Store them in a sealed polyethylene bag. If properly sealed, there is no need for the dessicant.

(2) Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C, and keep the relative humidity between 40%RH and 60%RH.

(3) The polarizer surface should not come in contact with any other objects. (We advise you to store them in the anti-static electricity container in which they were shipped.

Others

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

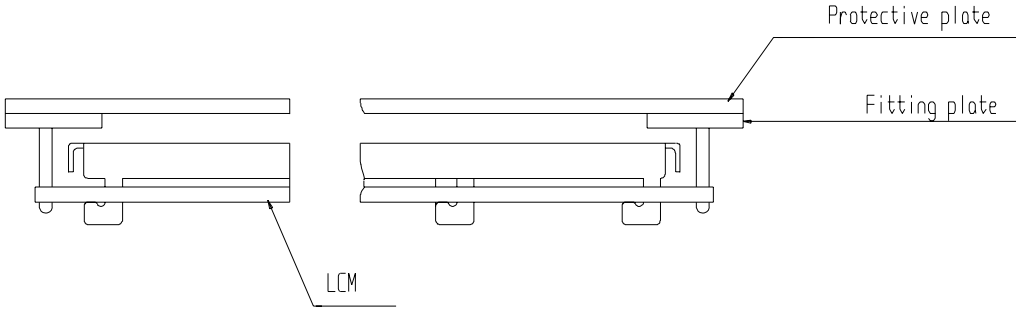
- Exposed area of the printed circuit board.
-Terminal electrode sections.

USING LCD MODULES

Installing LCD Modules

The hole in the printed circuit board is used to fix LCM as shown in the picture below. Attend to the following items when installing the LCM.

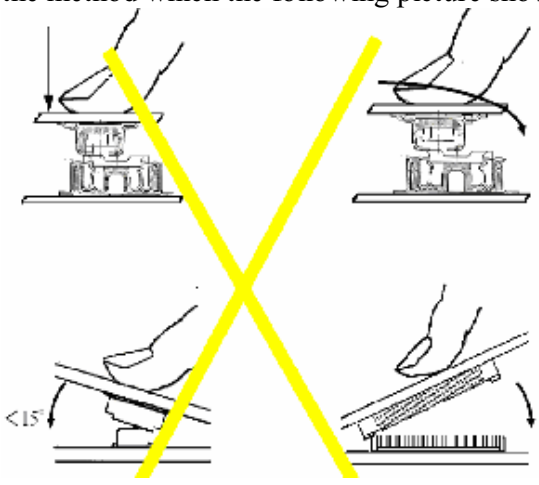
(1) Cover the surface with a transparent protective plate to protect the polarizer and LC cell.

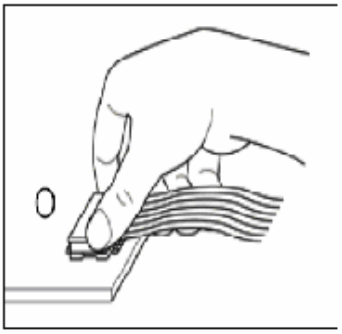


(2) When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be ±0.1mm.

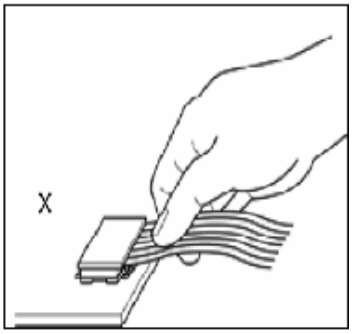
Precaution for assemble the module with BTB connector:

Please note the position of the male and female connector position,don't assemble or assemble like the method which the following picture shows





OK



NG

Precaution for soldering to the LCM

	Hand soldering	Machine drag soldering	Machine press soldering
No ROHS product	290°C ~350°C. Time : 3-5S.	330°C ~350°C. Speed : 4-8 mm/s.	300°C ~330°C. Time : 3-6S. Press: 0.8~1.2Mpa
ROHS product	340°C ~370°C. Time : 3-5S.	350°C ~370°C. Time : 4-8 mm/s.	330°C ~360°C. Time : 3-6S. Press: 0.8~1.2Mpa

(1) If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation. (This does not apply in the case of a non-halogen type of flux.) It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage due to flux spatters.

(2) When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.

(3) When remove the electroluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

Precautions for Operation

(1) Viewing angle varies with the change of liquid crystal driving voltage (VLCD). Adjust VLCD to show the best contrast.

(2) It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life. An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.

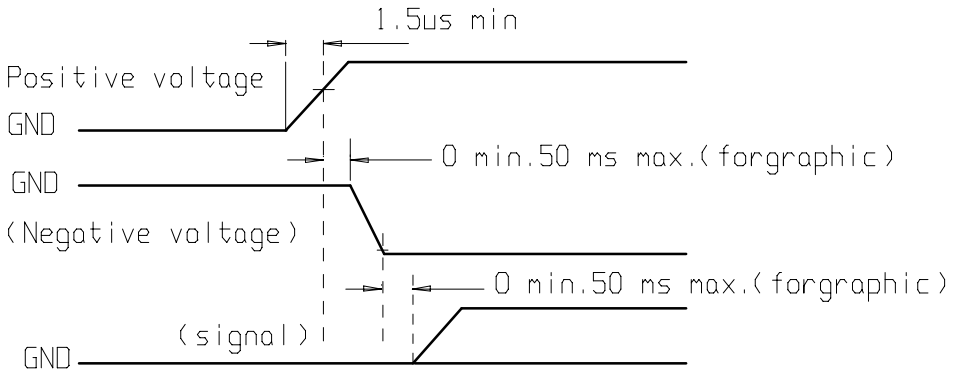
(3) Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, Which will come back in the specified operating temperature.

(4) If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and then back on.

(5) A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit. Usage under the maximum operating temperature,50%RH or less is required.

(6) Input each signal after the positive/negative voltage becomes stable.

(7) Please keep the temperature within specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity.



Safety

(1) It is recommended to crush damaged or unnecessary LCDs into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.

(2) If any liquid leaks out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water.

Limited Warranty

Unless agreed betweenMulti-Inno and customer,Multi-Inno will replace or repair any of its LCD modules which are found to be functionally defective when inspected in accordance with Multi-Inno LCD acceptance standards (copies available upon request) for a period of one year from date of production. Cosmetic/visual defects must be returned to Multi-Inno within 90 days of shipment. Confirmation of such date shall be based on data code on product. The warranty liability of Multi-Inno limited to repair and/or replacement on the terms set forth above. Multi-Inno will not be responsible for any subsequent or consequential events.

Return LCM under warranty

No warranty can be granted if the precautions stated above have been disregarded. The typical examples of violations are :

- Broken LCD glass.
- PCB eyelet is damaged or modified.
- PCB conductors damaged.
- Circuit modified in any way, including addition of components.
- PCB tampered with by grinding, engraving or painting varnish.
- Soldering to or modifying the bezel in any manner.

Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects. Any connectors or cable installed by the customer must be removed completely without damaging the PCB eyelet, conductors and terminals.

■ PRIOR CONSULT MATTER

1.①For Multi-Inno standard products, we keep the right to change material, process ... for improving the product property without notice on our customer.

②For OEM products, if any change needed which may affect the product property, we will consult with our customer in advance.

2. If you have special requirement about reliability condition, please let us know before you start the test on our samples.